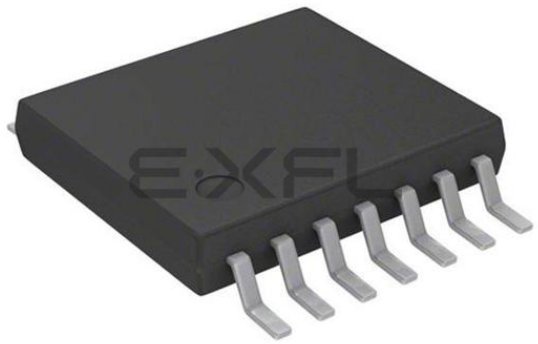

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	14-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	14-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1574t-i-st

3.3.2 SPECIAL FUNCTION REGISTER

The Special Function Registers are registers used by the application to control the desired operation of peripheral functions in the device. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh). The registers associated with the operation of the peripherals are described in the appropriate peripheral chapter of this data sheet.

3.3.3 GENERAL PURPOSE RAM

There are up to 80 bytes of GPR in each data memory bank. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh).

3.3.3.1 Linear Access to GPR

The general purpose RAM can be accessed in a non-banked method via the FSRs. This can simplify access to large memory structures. See **Section 3.6.2 "Linear Data Memory"** for more information.

3.3.4 COMMON RAM

There are 16 bytes of common RAM accessible from all banks.

3.3.5 DEVICE MEMORY MAPS

The memory maps are as shown in Table 3-3 through Table 3-13.

FIGURE 3-3: BANKED MEMORY PARTITIONING

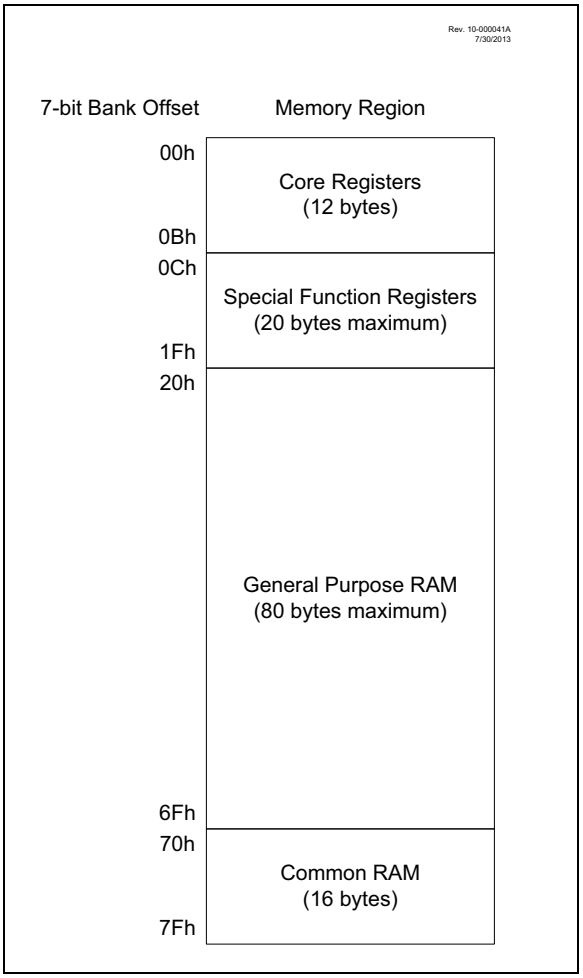
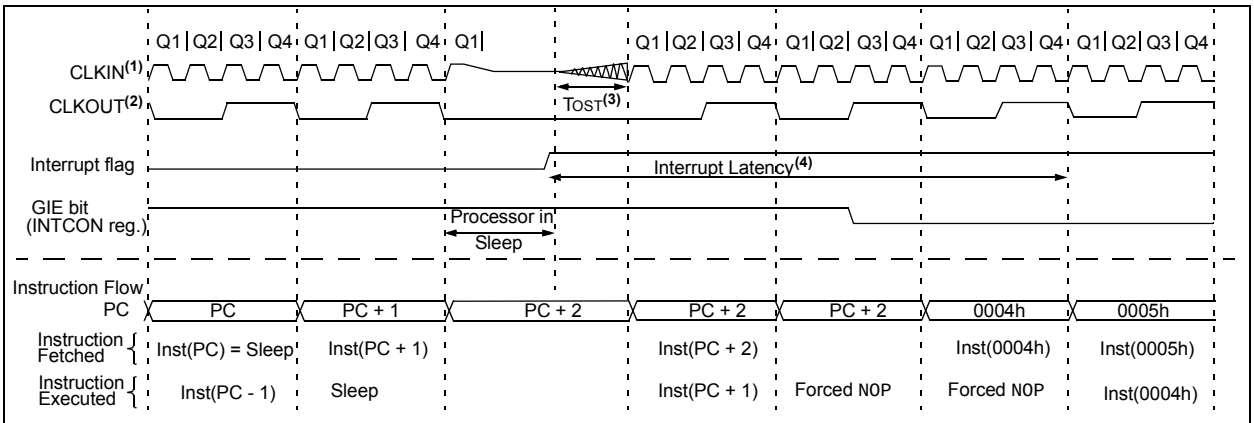


TABLE 3-13: PIC16(L)F1574/5/8/9 MEMORY MAP, BANK 31

Bank 31	
F8Ch	Unimplemented Read as '0'
FE3h	
FE4h	STATUS_SHAD
FE5h	WREG_SHAD
FE6h	BSR_SHAD
FE7h	PCLATH_SHAD
FE8h	FSR0L_SHAD
FE9h	FSR0H_SHAD
FEAh	FSR1L_SHAD
FEBh	FSR1H_SHAD
FECh	—
FEDh	STKPTR
FEEh	TOSL
FEFh	TOSH

Legend: = Unimplemented data memory locations, read as '0'.

FIGURE 8-1: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: External clock. High, Medium, Low mode assumed.
2: CLKOUT is shown here for timing reference.
3: TOST = 1024 TOSC. This delay does not apply to EC, RC and INTOSC Oscillator modes or Two-Speed Start-Up (if available).
4: GIE = 1 assumed. In this case after wake-up, the processor calls the ISR at 0004h. If GIE = 0, execution will continue in-line.

8.2 Low-Power Sleep Mode

This device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode.

Low-Power Sleep mode allows the user to optimize the operating current in Sleep. Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register, putting the LDO and reference circuitry in a low-power state whenever the device is in Sleep.

8.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the Default Operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The Normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

8.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the Normal Power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)

The Complementary Waveform Generator (CWG) module can utilize the HFINTOSC oscillator as either a clock source or as an input source. Under certain conditions, when the HFINTOSC is selected for use with the CWG module, the HFINTOSC will remain active during Sleep. This will have a direct effect on the Sleep mode current.

Please refer to section **24.10 "Operation During Sleep"** for more information.

Note:	The PIC16LF1574/5/8/9 devices do not have a configurable Low-Power Sleep mode. PIC16LF1574/5/8/9 are unregulated devices and are always in the lowest power state when in Sleep, with no wake-up time penalty. These devices have a lower maximum VDD and I/O voltage than the PIC16F1574/5/8/9 devices. See **Section 27.0 "Electrical Specifications"** for more information.

10.0 FLASH PROGRAM MEMORY CONTROL

The Flash program memory is readable and writable during normal operation over the full VDD range. Program memory is indirectly addressed using Special Function Registers (SFRs). The SFRs used to access program memory are:

- PMCON1
- PMCON2
- PMDATL
- PMDATH
- PMADRL
- PMADRH

When accessing the program memory, the PMDATH:PMDATL register pair forms a 2-byte word that holds the 14-bit data for read/write, and the PMADRH:PMADRL register pair forms a 2-byte word that holds the 15-bit address of the program memory location being read.

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump.

The Flash program memory can be protected in two ways; by code protection ($\overline{CP}$ bit in Configuration Words) and write protection (WRT<1:0> bits in Configuration Words).

Code protection ($\overline{CP}$ = 0)**(1)**, disables access, reading and writing, to the Flash program memory via external device programmers. Code protection does not affect the self-write and erase functionality. Code protection can only be reset by a device programmer performing a Bulk Erase to the device, clearing all Flash program memory, Configuration bits and User IDs.

Write protection prohibits self-write and erase to a portion or all of the Flash program memory as defined by the bits WRT<1:0>. Write protection does not affect a device programmers ability to read, write or erase the device.

Note 1:	Code protection of the entire Flash program memory array is enabled by clearing the $\overline{CP}$ bit of Configuration Words.

10.1 PMADRL and PMADRH Registers

The PMADRH:PMADRL register pair can address up to a maximum of 16K words of program memory. When selecting a program address value, the MSB of the address is written to the PMADRH register and the LSB is written to the PMADRL register.

10.1.1 PMCON1 AND PMCON2 REGISTERS

PMCON1 is the control register for Flash program memory accesses.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared by hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation to occur. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and execute the appropriate error handling routine.

The PMCON2 register is a write-only register. Attempting to read the PMCON2 register will return all '0's.

To enable writes to the program memory, a specific pattern (the unlock sequence), must be written to the PMCON2 register. The required unlock sequence prevents inadvertent writes to the program memory write latches and Flash program memory.

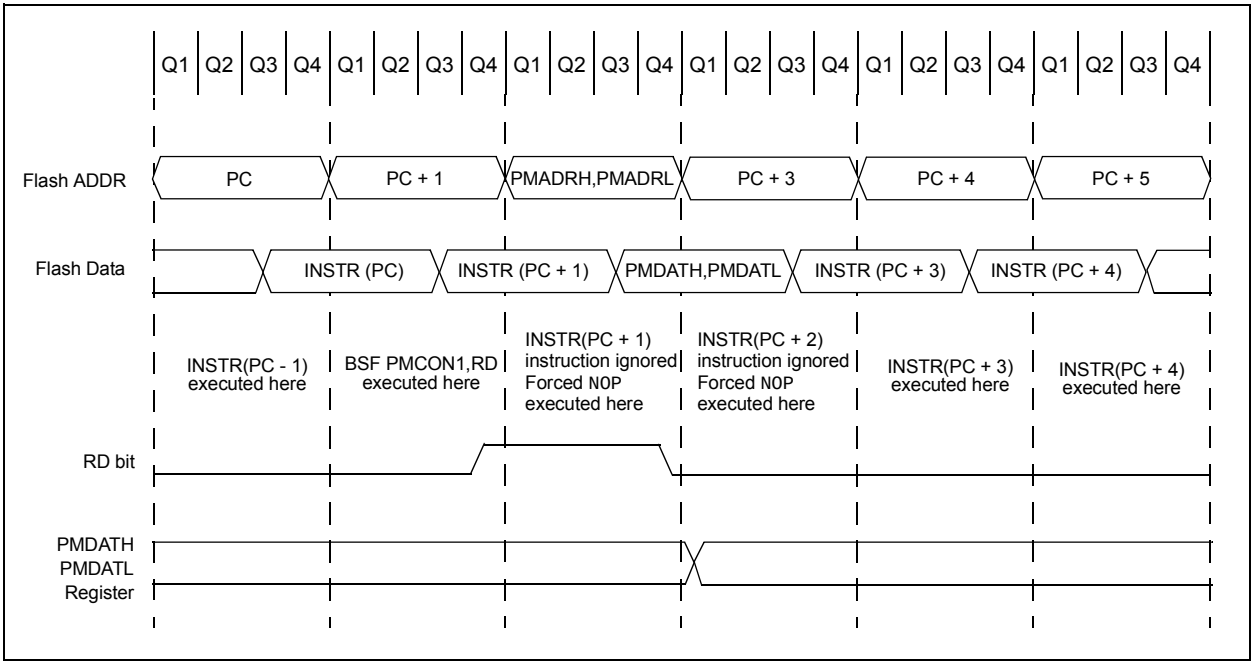
10.2 Flash Program Memory Overview

It is important to understand the Flash program memory structure for erase and programming operations. Flash program memory is arranged in rows. A row consists of a fixed number of 14-bit program memory words. A row is the minimum size that can be erased by user software.

After a row has been erased, the user can reprogram all or a portion of this row. Data to be written into the program memory row is written to 14-bit wide data write latches. These write latches are not directly accessible to the user, but may be loaded via sequential writes to the PMDATH:PMDATL register pair.

Note:	If the user wants to modify only a portion of a previously programmed row, then the contents of the entire row must be read and saved in RAM prior to the erase. Then, new data and retained data can be written into the write latches to reprogram the row of Flash program memory. However, any unprogrammed locations can be written without first erasing the row. In this case, it is not necessary to save and rewrite the other previously programmed locations.

FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWF    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-2)
    NOP                       ; Ignored (Figure 10-2)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

REGISTER 10-5: PMCON1: PROGRAM MEMORY CONTROL 1 REGISTER

U-1	R/W-0/0	R/W-0/0	R/W/HC-0/0	R/W/HC-x/q(2)	R/W-0/0	R/S/HC-0/0	R/S/HC-0/0
—(1)	CFGS	LWLO(3)	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **Unimplemented:** Read as '1'

bit 6 **CFGS:** Configuration Select bit
- 1 = Access Configuration, User ID and Device ID Registers
- 0 = Access Flash program memory

bit 5 **LWLO:** Load Write Latches Only bit(3)
- 1 = Only the addressed program memory write latch is loaded/updated on the next WR command
- 0 = The addressed program memory write latch is loaded/updated and a write of all program memory write latches will be initiated on the next WR command

bit 4 **FREE:** Program Flash Erase Enable bit
- 1 = Performs an erase operation on the next WR command (hardware cleared upon completion)
- 0 = Performs an write operation on the next WR command

bit 3 **WRERR:** Program/Erase Error Flag bit(2)
- 1 = Condition indicates an improper program or erase sequence attempt or termination (bit is set automatically on any set attempt (write '1') of the WR bit).
- 0 = The program or erase operation completed normally.

bit 2 **WREN:** Program/Erase Enable bit
- 1 = Allows program/erase cycles
- 0 = Inhibits programming/erasing of program Flash

bit 1 **WR:** Write Control bit
- 1 = Initiates a program Flash program/erase operation.
  The operation is self-timed and the bit is cleared by hardware once operation is complete.
  The WR bit can only be set (not cleared) in software.
- 0 = Program/erase operation to the Flash is complete and inactive.

bit 0 **RD:** Read Control bit
- 1 = Initiates a program Flash read. Read takes one cycle. RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
- 0 = Does not initiate a program Flash read.

Note 1: Unimplemented bit, read as '1'.
2: The WRERR bit is automatically set by hardware when a program memory write or erase operation is started (WR = 1).
3: The LWLO bit is ignored during a program memory erase operation (FREE = 1).

TABLE 11-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	121
INLVLA	—	—	INLVLA5	INLVLA4	INLVLA3	INLVLA2	INLVLA1	INLVLA0	123
LATA	—	—	LATA5	LATA4	—	LATA2	LATA1	LATA0	121
ODCONA	—	—	ODA5	ODA4	—	ODA2	ODA1	ODA0	122
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			178
PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	120
SLRCONA	—	—	SLRA5	SLRA4	—	SLRA2	SLRA1	SLRA0	123
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	120
WPUA	—	—	WPUA5	WPUA4	WPUA3	WPUA2	WPUA1	WPUA0	122

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTA.
Note 1: Unimplemented, read as '1'.

TABLE 11-3: SUMMARY OF CONFIGURATION WORD WITH PORTA

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	56
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>			

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by PORTA.

11.6 Register Definitions: PORTC

REGISTER 11-17: PORTC: PORTC REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RC7(2)	RC6(2)	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits(1, 2)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.
2: RC<7:6> are available on PIC16(L)F1578/9 only.

REGISTER 11-18: TRISC: PORTC TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISC7(1)	TRISC6(1)	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits(1)
1 = PORTC pin configured as an input (tri-stated)
0 = PORTC pin configured as an output

Note 1: TRISC<7:6> are available on PIC16(L)F1578/9 only.

REGISTER 11-19: LATC: PORTC DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATC7(1)	LATC6(1)	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATC<7:0>**: PORTC Output Latch Value bits(1)

Note 1: LATC<7:6> are available on PIC16(L)F1578/9 only.
2: Writes to PORTC are actually written to corresponding LATC register. Reads from PORTC register is return of actual I/O pin values.

16.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

16.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

16.1.2 CHANNEL SELECTION

There are up to 15 channel selections available:

- AN<7:0> pins (PIC16(L)F1574/5 only)
- AN<11:0> pins (PIC16(L)F1578/9 only)
- Temperature Indicator
- DAC1_output
- FVR_buffer1

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay (T_{ACQ}) is required before starting the next conversion. Refer to **Section 16.2.6 "ADC Conversion Procedure"** for more information.

16.1.3 ADC VOLTAGE REFERENCE

The ADC module uses a positive and a negative voltage reference. The positive reference is labeled ref+ and the negative reference is labeled ref-.

The positive voltage reference (ref+) is selected by the ADPREF bits in the ADCON1 register. The positive voltage reference source can be:

- V_{REF}+ pin
- V_{DD}
- FVR_buffer1

The negative voltage reference (ref-) source is:

- V_{SS}

16.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- FRC (internal RC oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 16-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the ADC conversion requirements in **Section 27.0 "Electrical Specifications"** for more information. Table 16-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

17.0 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC) MODULE

The Digital-to-Analog Converter supplies a variable voltage reference, ratiometric with the input source, with 32 selectable output levels.

The positive input source (VSOURCE+) of the DAC can be connected to:

- External VREF+ pin
- VDD supply voltage
- FVR_buffer1

The negative input source (VSOURCE-) of the DAC can be connected to:

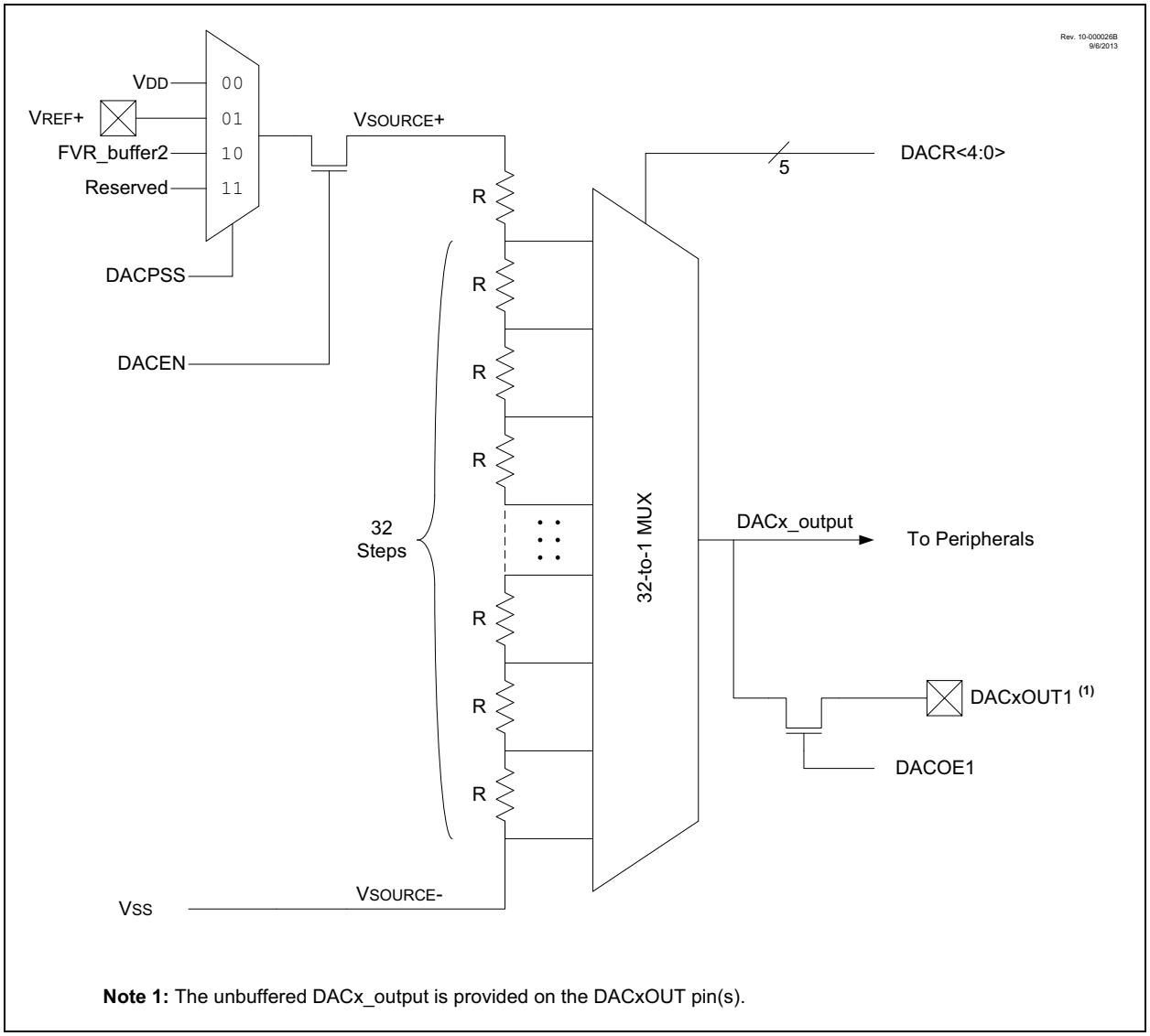
- Vss

The output of the DAC (DACx_output) can be selected as a reference voltage to the following:

- Comparator positive input
- ADC input channel
- DACxOUT1 pin

The Digital-to-Analog Converter (DAC) can be enabled by setting the DACEN bit of the DACxCON0 register.

FIGURE 17-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM



Note 1: The unbuffered DACx_output is provided on the DACxOUT pin(s).

FIGURE 20-6: TIMER1 GATE SINGLE-PULSE AND TOGGLE COMBINED MODE

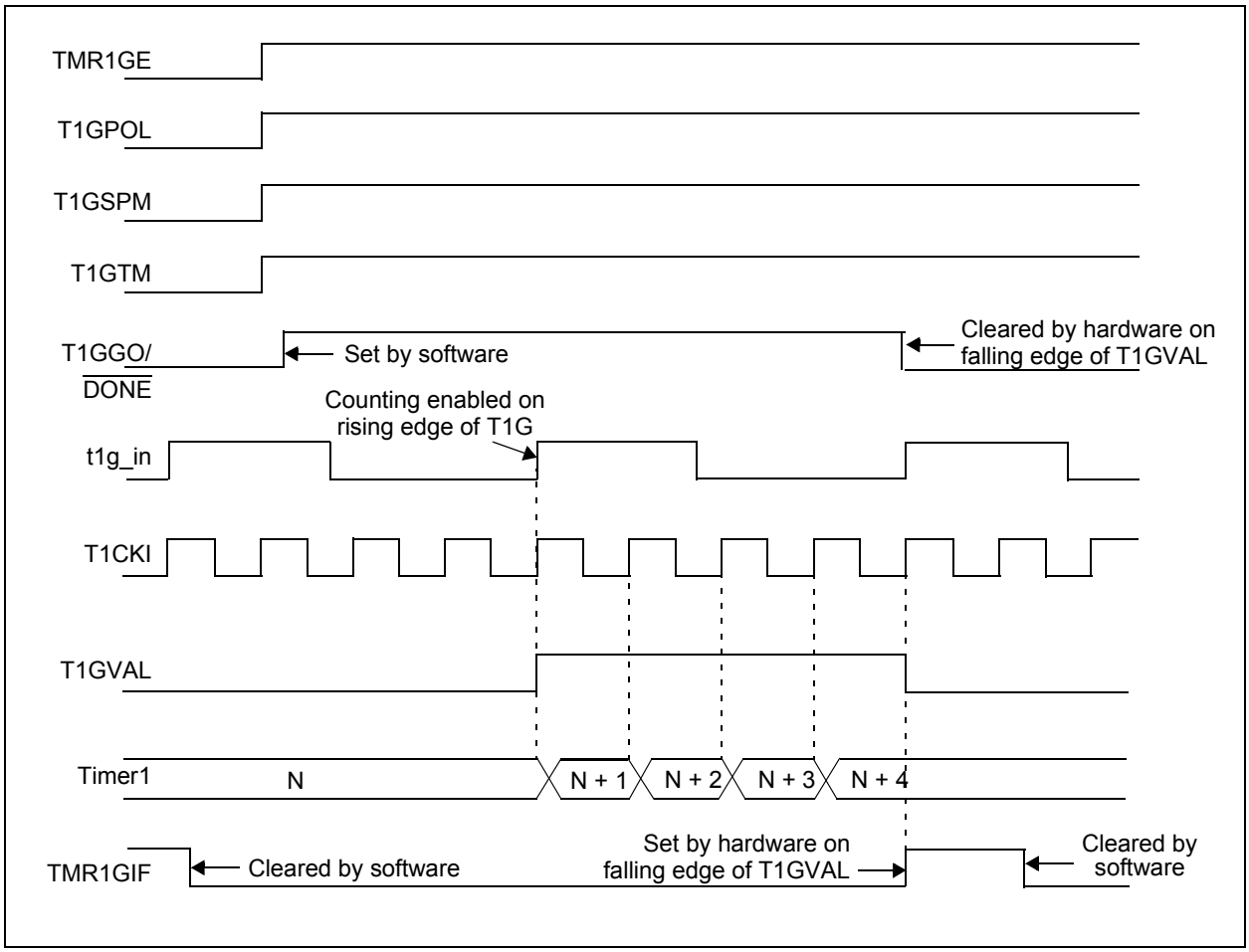


TABLE 22-2: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	204
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	—	—	TMR2IE	TMR1IE	87
PIR1	TMR1GIF	ADIF	RCIF	TXIF	—	—	TMR2IF	TMR1IF	90
RCREG	EUSART Receive Data Register								197*
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	203*
SPBRGL	BRG<7:0>								205*
SPBRGH	BRG<15:8>								205*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	202

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for asynchronous reception.

* Page provides register information.

TABLE 22-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	1221	1.73	255	1200	0.00	239	1202	0.16	207	1200	0.00	143
2400	2404	0.16	129	2400	0.00	119	2404	0.16	103	2400	0.00	71
9600	9470	-1.36	32	9600	0.00	29	9615	0.16	25	9600	0.00	17
10417	10417	0.00	29	10286	-1.26	27	10417	0.00	23	10165	-2.42	16
19.2k	19.53k	1.73	15	19.20k	0.00	14	19.23k	0.16	12	19.20k	0.00	8
57.6k	—	—	—	57.60k	0.00	7	—	—	—	57.60k	0.00	2
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	300	0.16	207	300	0.00	191	300	0.16	51
1200	1202	0.16	103	1202	0.16	51	1200	0.00	47	1202	0.16	12
2400	2404	0.16	51	2404	0.16	25	2400	0.00	23	—	—	—
9600	9615	0.16	12	—	—	—	9600	0.00	5	—	—	—
10417	10417	0.00	11	10417	0.00	5	—	—	—	—	—	—
19.2k	—	—	—	—	—	—	19.20k	0.00	2	—	—	—
57.6k	—	—	—	—	—	—	57.60k	0.00	0	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

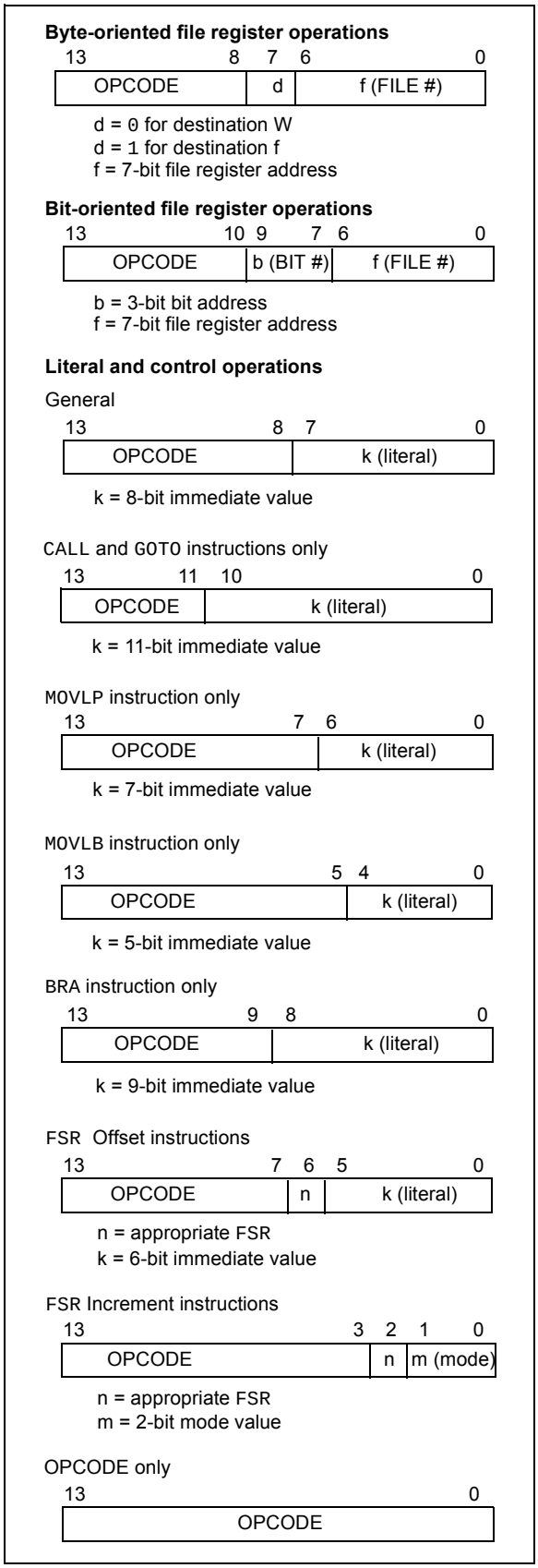
BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	—	—	—
9600	9615	0.16	129	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	10417	0.00	119	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	56.82k	-1.36	21	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	113.64k	-1.36	10	115.2k	0.00	9	111.1k	-3.55	8	115.2k	0.00	5

TABLE 22-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

FIGURE 26-1: GENERAL FORMAT FOR INSTRUCTIONS



BCF **Bit Clear f**

Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BRA **Relative Branch**

Syntax:	[*label*] BRA label [*label*] BRA $+k
Operands:	-256 ≤ label - PC + 1 ≤ 255 -256 ≤ k ≤ 255
Operation:	(PC) + 1 + k → PC
Status Affected:	None
Description:	Add the signed 9-bit literal 'k' to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + k. This instruction is a 2-cycle instruction. This branch has a limited range.

BRW **Relative Branch with W**

Syntax:	[*label*] BRW
Operands:	None
Operation:	(PC) + (W) → PC
Status Affected:	None
Description:	Add the contents of W (unsigned) to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 1 + (W). This instruction is a 2-cycle instruction.

BSF **Bit Set f**

Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSC **Bit Test f, Skip if Clear**

Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

BTFSS **Bit Test f, Skip if Set**

Syntax:	[*label*] BTFSS f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2-cycle instruction.

27.4 AC Characteristics

Timing Parameter Symbology has been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

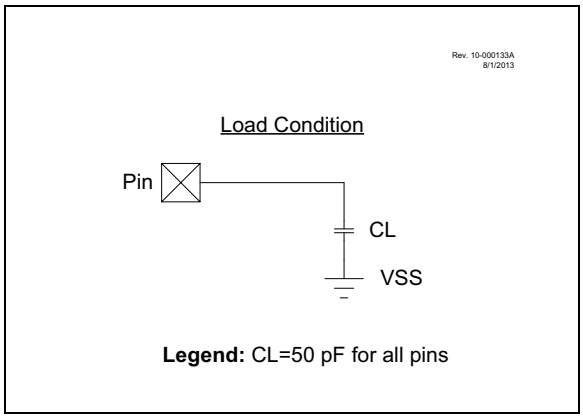
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	CLKIN
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDIx	sc	SCKx
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 27-4: LOAD CONDITIONS



Legend: CL=50 pF for all pins

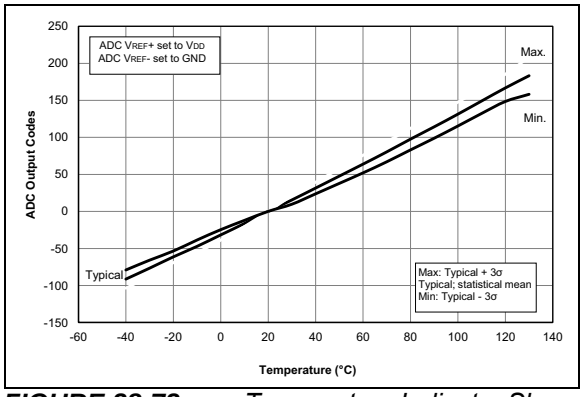
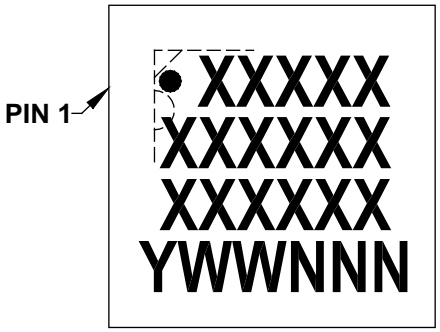


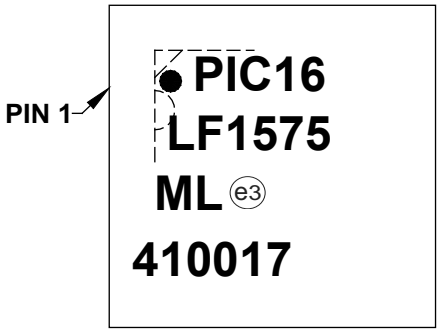
FIGURE 28-73: *Temperature Indicator Slope Normalized TO 20°C, High Range, VDD = 3.6V, LF Devices Only.*

Package Marking Information (Continued)

16-Lead UQFN (4x4x0.5mm)



Example

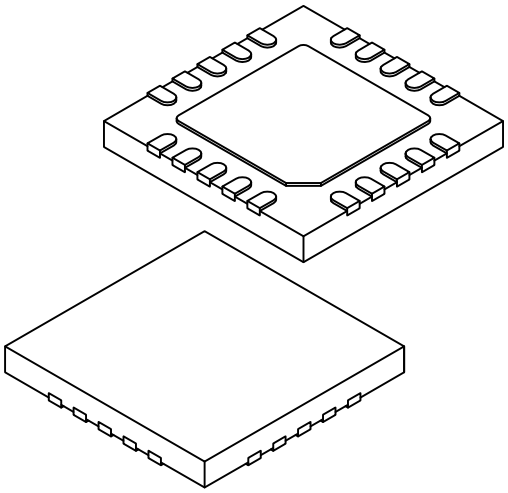


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		20	
Pitch	e		0.50 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.60	2.70	2.80
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-255A Sheet 2 of 2